

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HAJIME WATANABE	03/18/2016
TAKASHI FURUSAWA	03/18/2016
SATOSHI OGAWA	03/11/2016
TOSHIKAZU TAKATA	04/08/2016
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14916008
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	1568152.101US9
<b>NAME OF SUBMITTER:</b>	GREGORY G. BENNETT
<b>SIGNATURE:</b>	/Gregory G. Bennett/

<b>DATE SIGNED:</b>	10/03/2016
<b>Total Attachments: 3</b> source=101US9_ASN#page1.tif source=101US9_ASN#page2.tif source=101US9_ASN#page3.tif	

# ASSIGNMENT

Whereas, I/we,

NameAddress

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2) Takashi FURUSAWA

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4) Toshikazu TAKATA

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hereinafter called assignor(s), have invented certain improvements in

**POLYARYLENE SULFIDE RESIN, MANUFACTURING METHOD THEREFOR, AND MOLDING**

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on March 2, 2016, Serial No. 14/916008; and

Whereas

DIC Corporation

35-58, Sakashita 3-chome,  
Itabashi-ku, Tokyo 174-8520 Japan

and, National University Corporation, Iwate University

3-18-8, Ueda,  
Morioka-shi, Iwate 020-8550 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORSDATE SIGNED

1):

Name :

Hajime Watanabe

Hajime WATANABE

3/18. 2016

2):

Name :

T. Furusawa

Takashi FURUSAWA

3/18. 2016

3) :

Name :

Satoshi OGAWA

4) :

Name :

*Toshikazu Takata*

Toshikazu TAKATA

*4/8, 2016*

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)

Page 2 of 2

PATENT  
REEL: 039924 FRAME: 0085

3) : *Satoshi Ogawa* *March 11, 2016*  
Name : Satoshi OGAWA

4) : \_\_\_\_\_  
Name : Toshikazu TAKATA